The 8th International Symposium on Biomedical Engineering (ISBE) and International Workshop on Nanodevice Technologies 2023 (IWNT)

Sponsored by Ministry of Education, Culture, Sports, Science and Technology (MEXT)

November 21-22, 2023

Invited Speakers

H. Wakabayashi

Tokyo Inst. Tech., Japan

Z. Holman

Arizona State Univ., USA

S. Kuroki

Hiroshima Univ., Japan

J. Christen

Arizona State Univ., USA

J. Jang

Univ. of Tokyo, Japan

H. Fu

Arizona State Univ., USA

X. Xing

Tsinghua University, China

J. Ishihara

Imperial College London, UK

お申し込み・お問い合わせ先

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東京工業大学 **FIRST**





Venue: Satake Memorial Hall, Hiroshima University

(Higashihiroshima Campus, Hiroshima, Japan) Access: JR Sanyo Main Line Saijo station, Bus 15 min

広島大学 東広島キャンパス サタケメモリアルホール (JR山陽本線西条駅バス15分)

The Research Center of Biomedical Engineering (RCBE) was established in April, 2016, by support of the Ministry of Education, Culture, Sports, Science and Technology (MEXT). The international symposium on biomedical engineering is organized as a part of the activities in the RCBE. Through the collaborative research between medicine and engineering, we discuss the global issues on future medicine and healthcare to realize a healthy aging society. This symposium is organized jointly with Workshop on Nanodevice Technologies to promote research and discussion with nanodevice science technologies.

Organizers:

 Institute of Biomaterials and Bioengineering, Tokyo Medical and Dental University

· Laboratory for Future Interdisciplinary Research of Science and Technology, Tokyo Institute of Technologies

Research Institute for Nanodevices, **Hiroshima University**

Research Institute of Electronics, Shizuoka University

(ISBE) 主催:東京医科歯科大学 生体材料工学研究所

東京工業大学 未来産業技術研究所

広島大学 ナノデバイス研究所

静岡大学 電子工学研究所

(IWNT) 主催:広島大学 ナノデバイス研究所

協賛: せとうち半導体共創コンソーシアム

Submission deadline for poster presentation: Oct. 23, 2023 The abstract submission is required for poster presentation.

Registration deadline: Oct. 27, 2023

Registration is free. Pre-registration is preferable.

ポスター発表申込締切 2023年10月23日(月)

参加申込締切 2023年10月27日(金)

Networking fee:

JPY6,000 for regular participants, and JPY2,000 for students. The networking fee should be paid on site at the registration desk. Registration for the networking is required.

懇談会参加費: 6,000円 (学生 2,000円)